

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently amended) Optical interconnection module comprising a package provided with at least one optical section interposed between an input optical port of the module and an output optical port of the module, characterized in that the optical section is overmolded in the package and forms an optical waveguide, in that the optical fiber section comprises at least one flared cone getting enlarged at one end of the section and forming an optical input/output section, and in that the optical section comprises an end lens.
2. (Previously presented) A module according to claim 1, characterized in that the lens is formed by overmolding.
3. (Previously presented) A module according to claim 1, characterized in that the package is made of a material that has an optical refraction index lower than an optical refraction index of an overmolded material forming the optical section.
4. (Previously presented) A module according to claim 1, characterized in that the lens is made of a same material as that of the optical section.
5. (Previously presented) A module according to claim 1, characterized in that the package comprises a polymer material

with efficient thermal behavior such as, for example, an LCP, or a polyimide.

6. (Previously presented) A module according to claim 1, characterized in that the package is metallized.

7. (Previously presented) A module according to claim 1, characterized in that the package has a pedestal with gripping grooves.

8. (Previously presented) A module according to claim 1, characterized in that the overmolded optical section is curved to lead into a plane.

9. (Previously presented) An optical ferrule comprising a module according to claim 1, characterized in that the input optical port has a standardized receptacle.

10. (Previously presented) An optical ferrule comprising a module according to claim 1, characterized in that it comprises an electronic integrated circuit for the detection or emission of light rays, the integrated circuit being mounted by reflow soldering of solder beads on the package.